



LEXANT™ FR RESINS 940A

REGION AMERICAS

DESCRIPTION

LEXANT™ 940A resin is a 10 MFR polycarbonate. Mold release. Flame retardant, UL94 V0 rated. Available in transparent and translucent colors.

TYPICAL PROPERTY VALUES

Revision 20201125

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL			
Tensile Stress, yld, Type I, 50 mm/min	62	MPa	ASTM D638
Tensile Stress, brk, Type I, 50 mm/min	55	MPa	ASTM D638
Tensile Strain, yld, Type I, 50 mm/min	7	%	ASTM D638
Tensile Strain, brk, Type I, 50 mm/min	90	%	ASTM D638
Flexural Stress, yld, 1.3 mm/min, 50 mm span	91	MPa	ASTM D790
Flexural Modulus, 1.3 mm/min, 50 mm span	2240	MPa	ASTM D790
Hardness, Rockwell M	70	-	ASTM D785
Hardness, Rockwell R	118	-	ASTM D785
Taber Abrasion, CS-17, 1 kg	10	mg/1000cy	ASTM D1044
IMPACT			
Izod Impact, unnotched, 23°C	3204	J/m	ASTM D4812
Izod Impact, notched, 23°C	640	J/m	ASTM D256
Tensile Impact Strength, Type S	525	kJ/m ²	ASTM D1822
Falling Dart Impact (D 3029), 23°C	169	J	ASTM D3029
THERMAL			
Vicat Softening Temp, Rate B/50	151	°C	ASTM D1525
HDT, 0.45 MPa, 6.4 mm, unannealed	137	°C	ASTM D648
HDT, 1.82 MPa, 6.4 mm, unannealed	132	°C	ASTM D648
CTE, -40°C to 95°C, flow	6.84E-05	1/°C	ASTM E831
Thermal Conductivity	0.19	W/m-°C	ASTM C177
Relative Temp Index, Elec	130	°C	UL 746B
Relative Temp Index, Mech w/impact	120	°C	UL 746B
Relative Temp Index, Mech w/o impact	130	°C	UL 746B
PHYSICAL			
Specific Gravity	1.21	-	ASTM D792
Specific Volume	0.83	cm ³ /g	ASTM D792
Density	1.217	g/cm ³	ASTM D792
Water Absorption, (23°C/24hrs)	0.15	%	ASTM D570
Water Absorption, (23°C/Saturated)	0.35	%	ASTM D570
Water Absorption, equilibrium, 100°C	0.58	%	ASTM D570
Mold Shrinkage, flow, 3.2 mm	0.5 – 0.7	%	SABIC method
Melt Flow Rate, 300°C/1.2 kgf	10	g/10 min	ASTM D1238
OPTICAL			
Light Transmission, 2.54 mm	85	%	ASTM D1003
Haze, 2.54 mm	1	%	ASTM D1003



PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Refractive Index	1.586	-	ASTM D542
ELECTRICAL			
Volume Resistivity	>1.E+17	Ω.cm	ASTM D257
Dielectric Strength, in air, 3.2 mm	16.7	kV/mm	ASTM D149
Relative Permittivity, 50/60 Hz	3.01	-	ASTM D150
Relative Permittivity, 1 MHz	2.96	-	ASTM D150
Dissipation Factor, 50/60 Hz	0.0009	-	ASTM D150
Dissipation Factor, 1 MHz	0.01	-	ASTM D150
Arc Resistance, Tungsten {PLC}	7	PLC Code	ASTM D495
Hot Wire Ignition {PLC}	2	PLC Code	UL 746A
High Voltage Arc Track Rate {PLC}	3	PLC Code	UL 746A
High Ampere Arc Ign, surface {PLC}	3	PLC Code	UL 746A
Comparative Tracking Index (UL) {PLC}	2	PLC Code	UL 746A
FLAME CHARACTERISTICS			
UL Yellow Card Link	E121562-100175209	-	-
UL Recognized, 94V-2 Flame Class Rating	1.5	mm	UL 94
UL Recognized, 94V-0 Flame Class Rating	3.0	mm	UL 94
Radiant Panel Listing	<input checked="" type="checkbox"/>	-	UL Tested
Oxygen Index (LOI)	35	%	ISO 4589
INJECTION MOLDING			
Drying Temperature	120	°C	
Drying Time	3 – 4	Hrs	
Drying Time (Cumulative)	48	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	295 – 315	°C	
Nozzle Temperature	290 – 310	°C	
Front - Zone 3 Temperature	295 – 315	°C	
Middle - Zone 2 Temperature	280 – 305	°C	
Rear - Zone 1 Temperature	215 – 295	°C	
Mold Temperature	70 – 95	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	40 – 70	rpm	
Shot to Cylinder Size	40 – 60	%	
Vent Depth	0.025 – 0.076	mm	

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